



Attorney, Docket No. YUSO-131

2CE/2800  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Hsieh et al.  
Title: Formation of electroplate solder on an organic  
Circuit board for flip chip joints and board to board solder  
joints  
Appl. No.: 10/052,989  
Filing Date: November 9, 2001  
Examiner: David Vu  
Art Unit: 2818

**REQUEST FOR CONTINUED EXAMINATION (RCE)**  
**AND TRANSMITTAL**

Mail Stop RCE  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

This is a Request for Continued Examination (RCE) under 37 CFR 1.114 of the above-identified application.

1. Submission required under 37 C.F.R. §1.114: (check items that apply)

a. Previously submitted:

- ☐ Consider the amendment/(s)reply under 37 C.F.R. §1.116 previously filed on \_\_\_\_\_.
- ☐ Consider the arguments in the Appeal Brief or Reply Brief previously filed on \_\_\_\_\_.
- ☐ Other \_\_\_\_\_.

b. Enclosed:

- ☒ Amendment Accompanying Request for Continued Examination.
- ☐ Affidavit(s)/Declaration(s).
- ☐ Information Disclosure Statement
- ☐ Other \_\_\_\_\_.

03/08/2004 CNGUYEN 00000090 10052989

01 FC:1801 <sup>2</sup> Miscellaneous: 770.00 0P

- ☐ Suspension of action on the above-identified application is requested under 37 C.F.R. §1.103(c) for a period of \_\_\_\_\_ months.

3. Fees as calculated below:

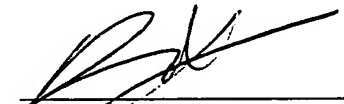
	Claims As Amended	Previously Paid For	Extra Claims	Rate		Fee Totals
RCE Fee 1.17(e)				X \$770	=	770
Total Claims:	20	23	-0-	X \$18	=	-0-
Independents:	2	4	-0-	X \$86	=	-0-
Statutory Disclaimer fee				X \$110	=	
Extension of Time fee				X \$	=	
SUBTOTAL:					=	770
[ ] Small Entity Fees Apply (subtract ½ of above):					=	
TOTAL FILING FEE:					=	770

A check in the amount of \$770 for filing fee is enclosed.

Please direct all correspondence to the undersigned attorney or agent at the address indicated below.

Respectfully submitted,

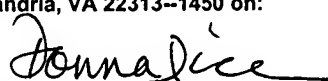
Date: 3-2-04

  
 Raymond Sun  
 Reg. No. 35,699

**CERTIFICATE OF MAILING**

I hereby certify that the above-identified document is being deposited with the U.S. Postal Service as First Class mail in an envelope addressed to Mail Stop RCE, Commissioner for Patents, PO Box 1450, Alexandria, VA 22313--1450 on:

Date: March 2, 2004

By:   
 Donna Dice



YUSO-131

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Hsieh et al.

Art Unit: 2818

Serial No.: 10/052,989

Examiner: David Vu

Filing Date: November 9, 2001

For: Formation of Electroplate  
Solder on an Organic Circuit  
Board for Flip Chip Joints and  
Board to Board Solder Joints

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AMENDMENT TO FINAL OFFICE ACTION DATED DECEMBER 2, 2003

In response to the Final Office Action dated December 2, 2003, Applicant is filing this Amendment together with a Request for Continued Examination. Please enter and consider the following amendments and remarks: